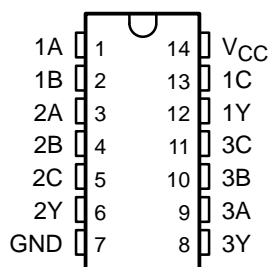


SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

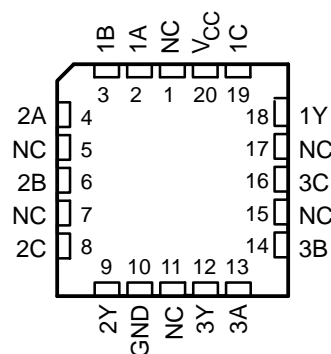
SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

- 4.5-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 5.5 ns at 5 V

SN54ALS11A, . . . J OR W PACKAGE
SN54AS11 . . . J PACKAGE
SN74ALS11A, SN74AS11 . . . D, N, OR NS PACKAGE
(TOP VIEW)



SN54ALS11A, SN54AS11 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These devices contain three independent 3-input positive-AND gates. They perform the Boolean functions $Y = A \cdot B \cdot C$ or $Y = \overline{A + B + C}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	PDIP – N	Tube	SN74ALS11AN	SN74ALS11AN	
			SN74AS11N	SN74AS11N	
	SOIC – D	Tube	SN74ALS11AD	ALS11A	
			Tape and reel		SN74ALS11ADR
			Tube	SN74AS11D	AS11
				Tape and reel	
SOP – NS	Tape and reel	SN74ALS11ANSR	ALS11A		
		SN74AS11NSR	74AS11		
–55°C to 125°C	CDIP – J	Tube	SNJ54ALS11AJ	SNJ54ALS11AJ	
			SNJ54AS11J	SNJ54AS11J	
	CFP – W	Tube	SNJ54ALS11AW	SNJ54ALS11AW	
			SNJ54ALS11AFK	SNJ54ALS11AFK	
LCCC – FK	Tube	SNJ54ALS11AFK	SNJ54ALS11AFK		
		SNJ54AS11FK	SNJ54AS11FK		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

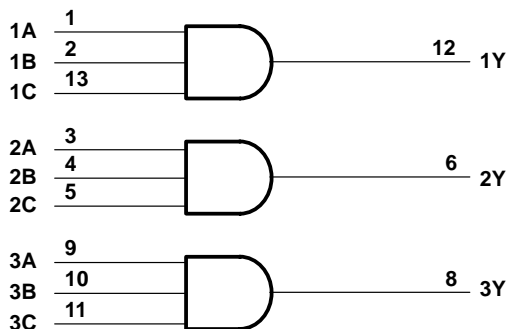
SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

FUNCTION TABLE
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	H
L	X	X	L
X	L	X	L
X	X	L	L

logic diagram, each gate (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

absolute maximum ratings over operating free-air temperature range (SN54ALS11A, SN74ALS11A) (unless otherwise noted)[†]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Package thermal impedance, θ_{JA} (see Note 1): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	SN54ALS11A			SN74ALS11A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8 [‡]			0.8	V
			0.7 [§]				
I_{OH} High-level output current			-0.4			-0.4	mA
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	-55		125	0		70	°C

[‡] Applies over temperature range -55°C to 70°C

[§] Applies over temperature range 70°C to 125°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS11A		SN74ALS11A		UNIT		
		MIN	TYP†	MAX	MIN		TYP†	MAX
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.5		-1.5	V	
V_{OH}	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -0.4\text{ mA}$			$V_{CC} - 2$		$V_{CC} - 2$	V	
V_{OL}	$V_{CC} = 4.5\text{ V}$			0.25	0.4	0.25	0.4	V
						0.35	0.5	
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$				0.1		0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$				20		20	μA
I_{IL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$				-0.1		-0.1	mA
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$			-20	-112	-30	-112	mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$, $V_I = 4.5\text{ V}$			1	1.8	1	1.8	mA
I_{CCL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0$			1.6	3	1.6	3	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V TO } 5.5\text{ V}$, $C_L = 50\text{ PF}$, $R_L = 500\ \Omega$, $T_A = \text{MIN TO MAX}\S$				UNIT
			SN54ALS11A		SN74ALS11A		
			MIN	MAX	MIN	MAX	
t_{PLH}	A, B, or C	Y	2	14	2	13	ns
t_{PHL}			2	12.5	2	10	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (SN54AS11, SN74AS11) (unless otherwise noted)¶

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Package thermal impedance, θ_{JA} (see Note 1): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range	-65°C to 150°C

¶ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

recommended operating conditions (see Note 2)

		SN54AS11			SN74AS11			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
V _{IH}	High-level input voltage	2			2			V	
V _{IL}	Low-level input voltage	0.8			0.8			V	
I _{OH}	High-level output current	-2			-2			mA	
I _{OL}	Low-level output current	20			20			mA	
T _A	Operating free-air temperature	-55			0			70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS11			SN74AS11			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA	-1.2			-1.2			V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -2 mA	V _{CC} -2			V _{CC} -2			V
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 20 mA	0.35 0.5			0.35 0.5			V
I _I	V _{CC} = 5.5 V, V _I = 7 V	0.1			0.1			mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V	20			20			μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V	-0.5			-0.5			mA
I _{O‡}	V _{CC} = 5.5 V, V _O = 2.25 V	-30 -112			-30 -112			mA
I _{CCH}	V _{CC} = 5.5 V, V _I = 4.5 V	4.3 7			4.3 7			mA
I _{CCL}	V _{CC} = 5.5 V, V _I = 0	11.2 18			11.2 18			mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

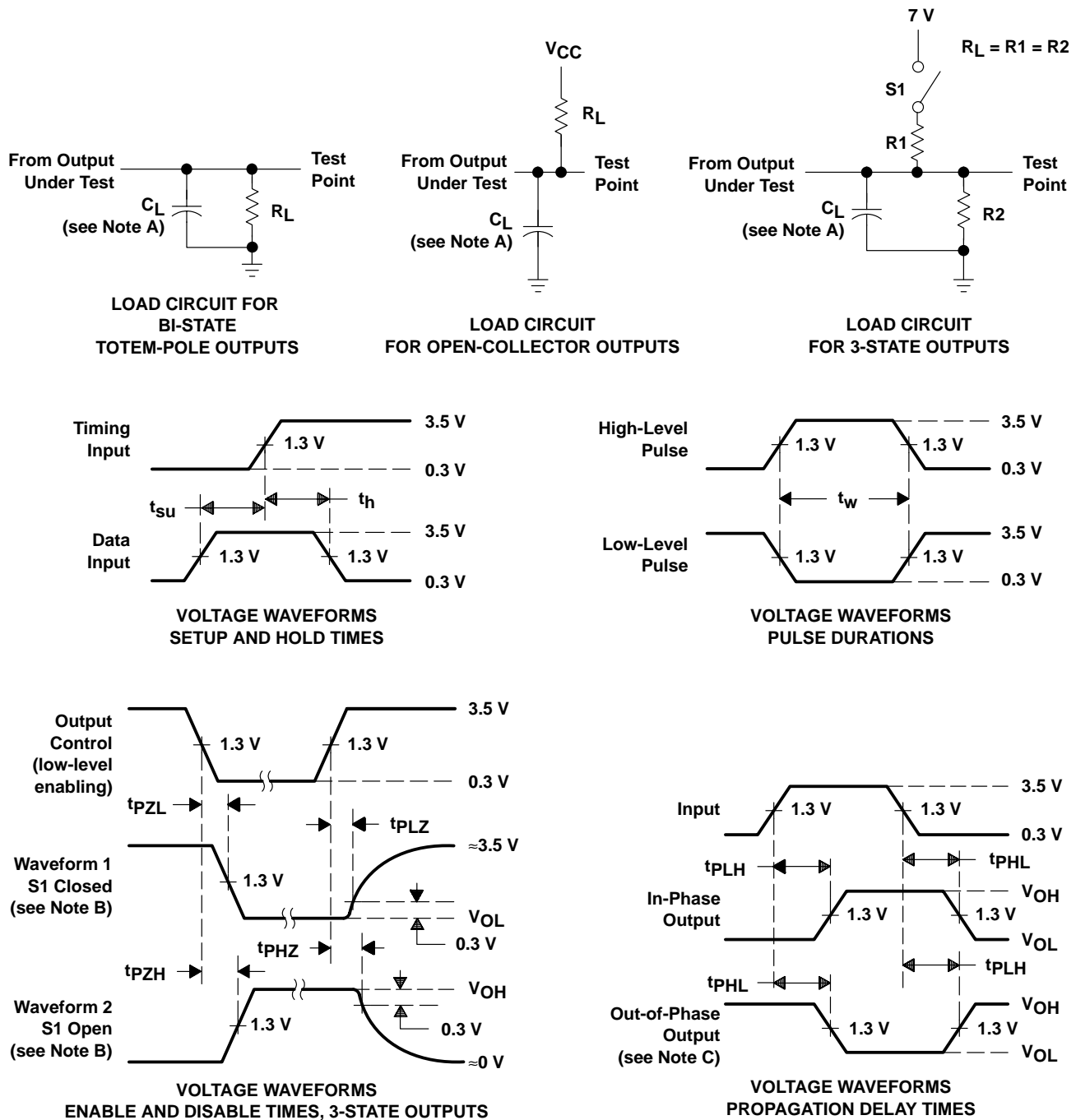
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V TO 5.5 V, C _L = 50 PF, R _L = 500 Ω, T _A = MIN TO MAX§				UNIT
			SN54AS11		SN74AS11		
			MIN	MAX	MIN	MAX	
t _{PLH}	A, B, or C	Y	1	6.5	1	6	ns
t _{PHL}			1	6.5	1	5.5	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-86841012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8684101CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-8684101DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
5962-9756101Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9756101QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
JM38510/37402B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/37402BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/37402B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/37402BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54ALS11AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54AS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74ALS11AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS11ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS11ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS11ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74AS11D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS11NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS11NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS11NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS11AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS11AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS11AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54AS11FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 :

● Catalog: [SN74ALS11A](#), [SN74AS11](#)

● Military: [SN54ALS11A](#), [SN54AS11](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS11ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS11ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS11DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS11NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

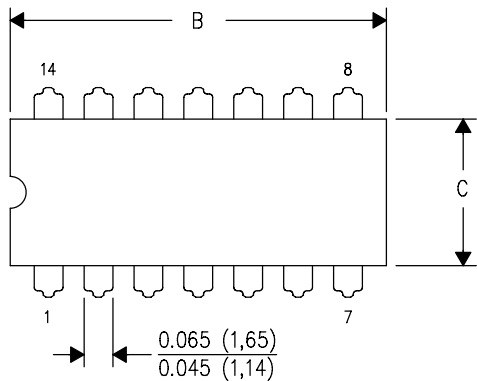

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS11ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS11ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS11DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS11NSR	SO	NS	14	2000	367.0	367.0	38.0

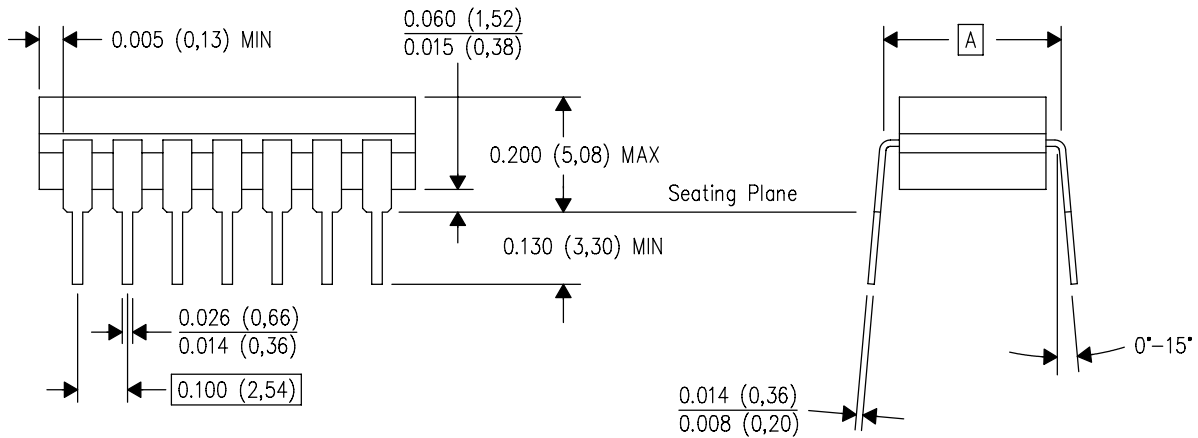
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

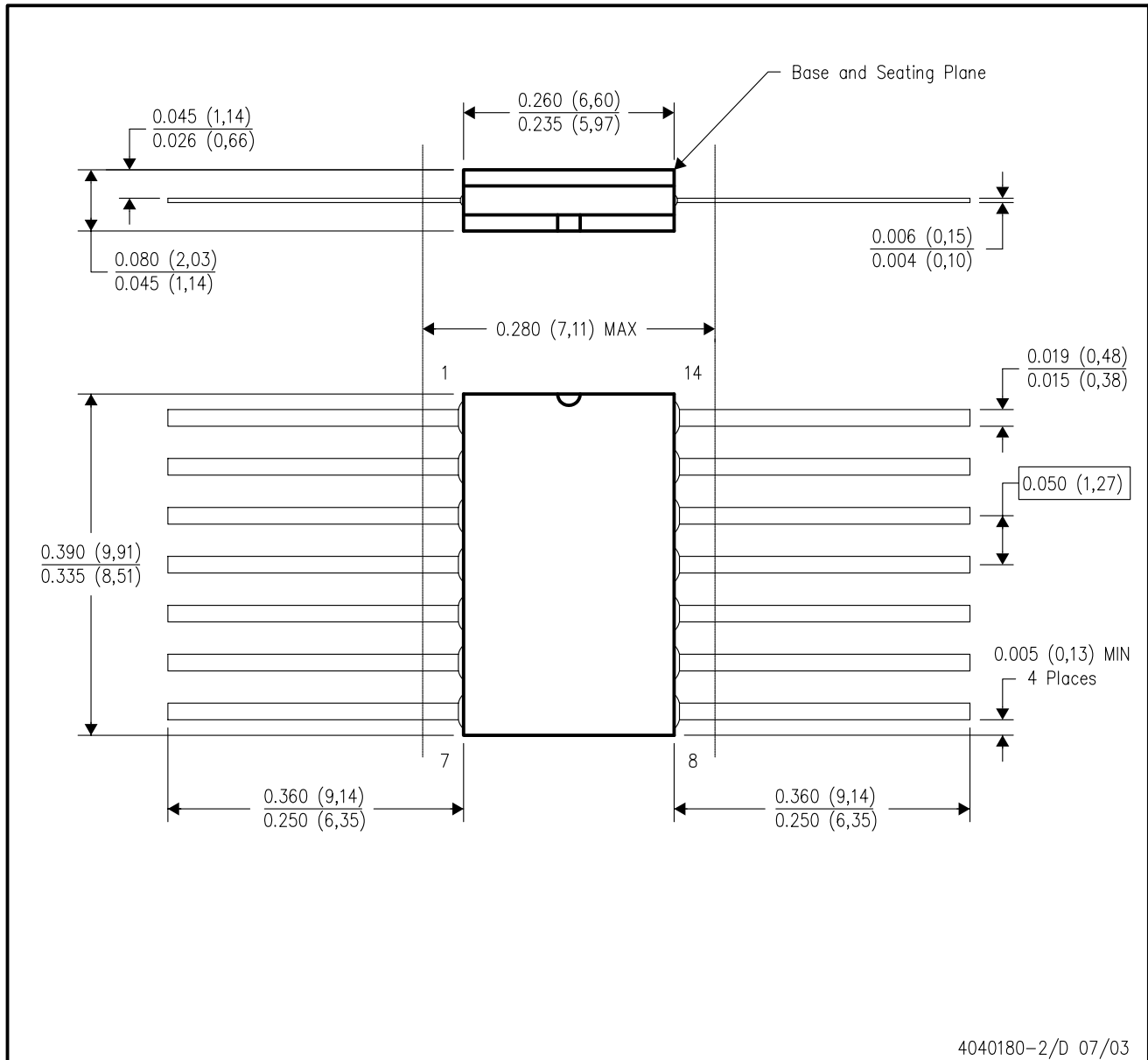


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

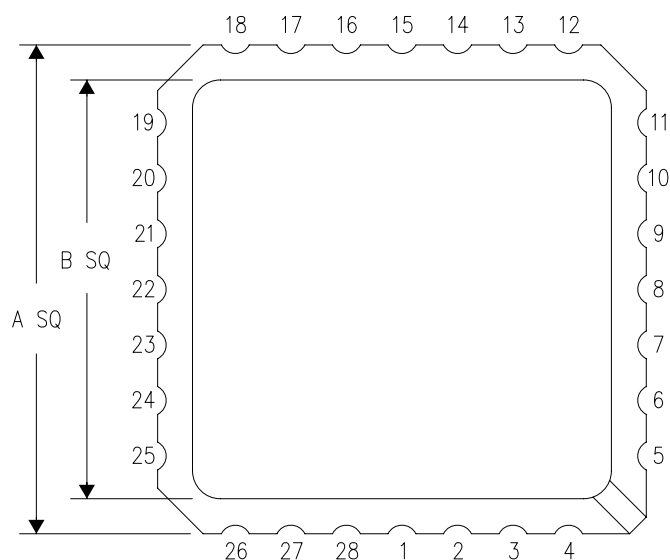


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

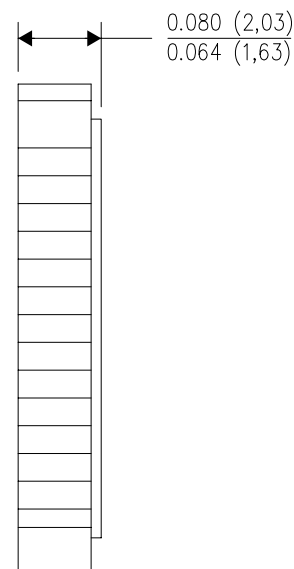
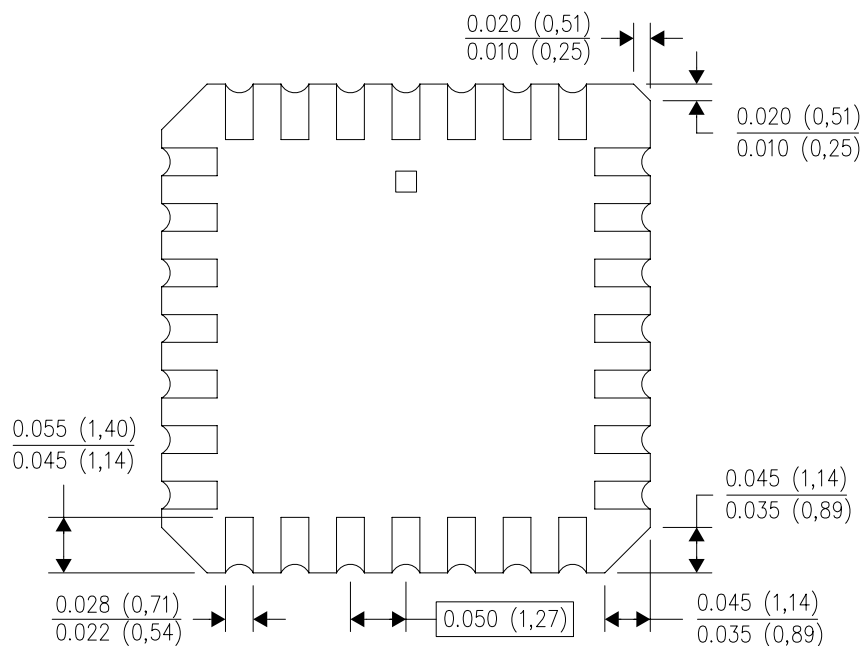
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



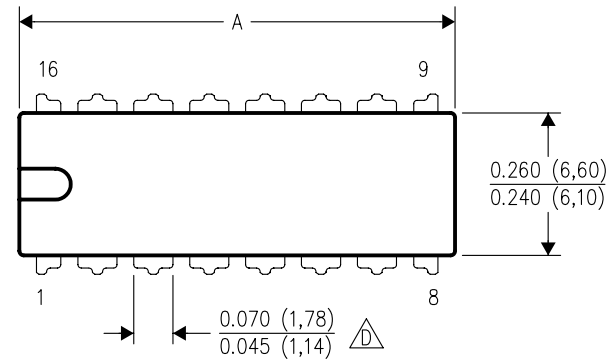
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

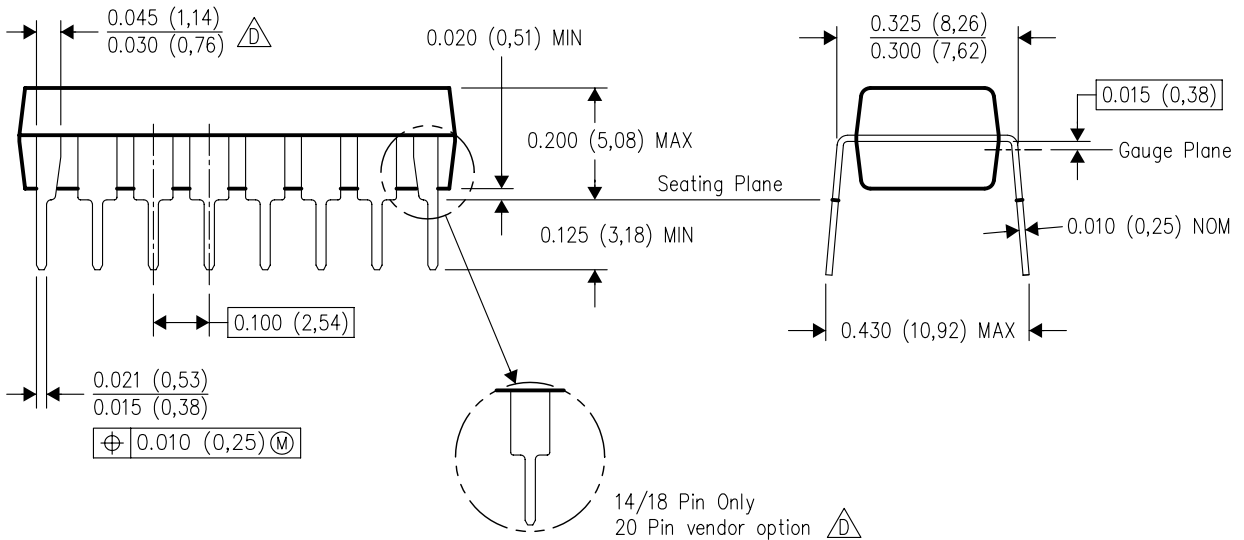
N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



DIM	PINS **			
	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

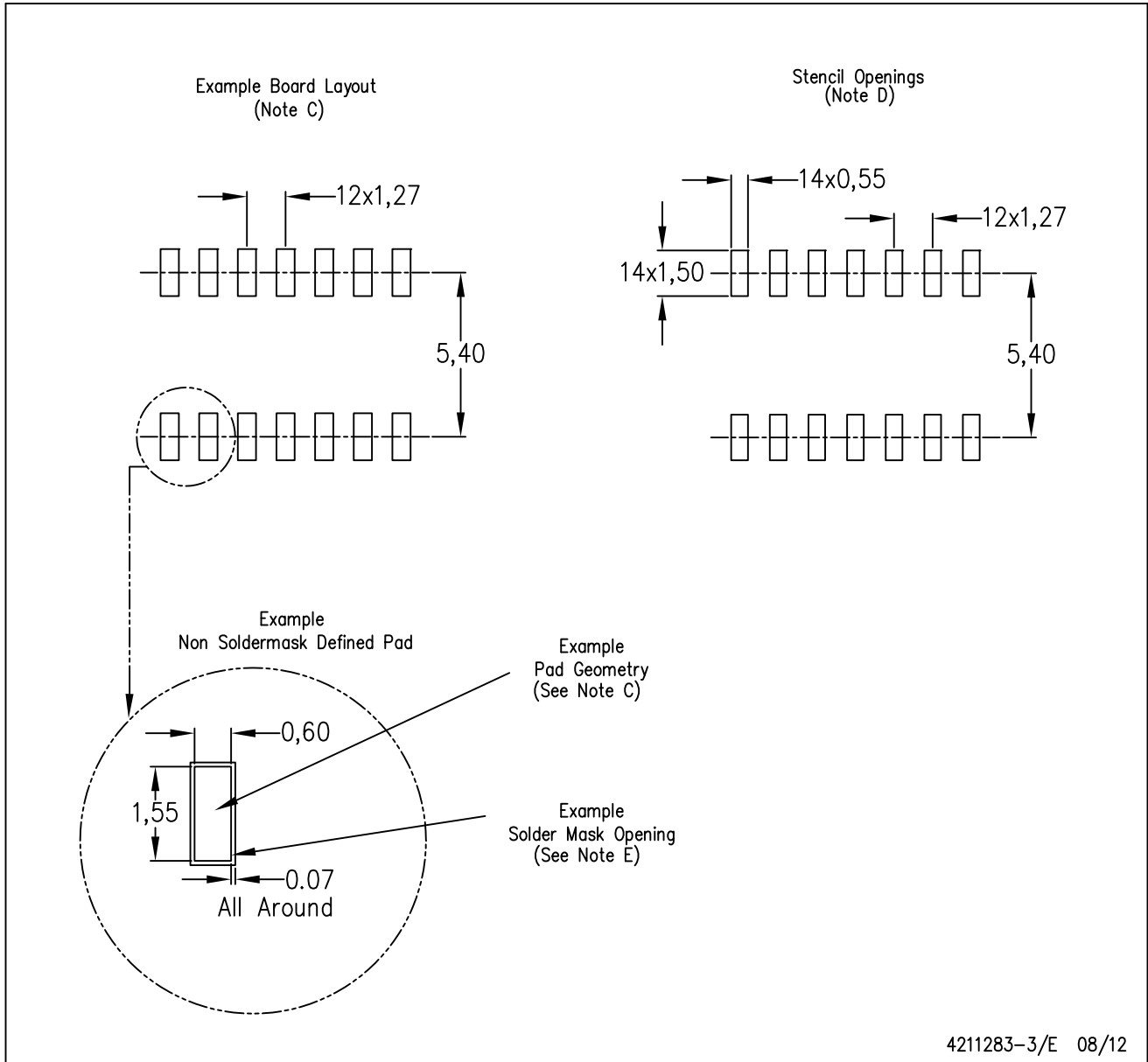


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



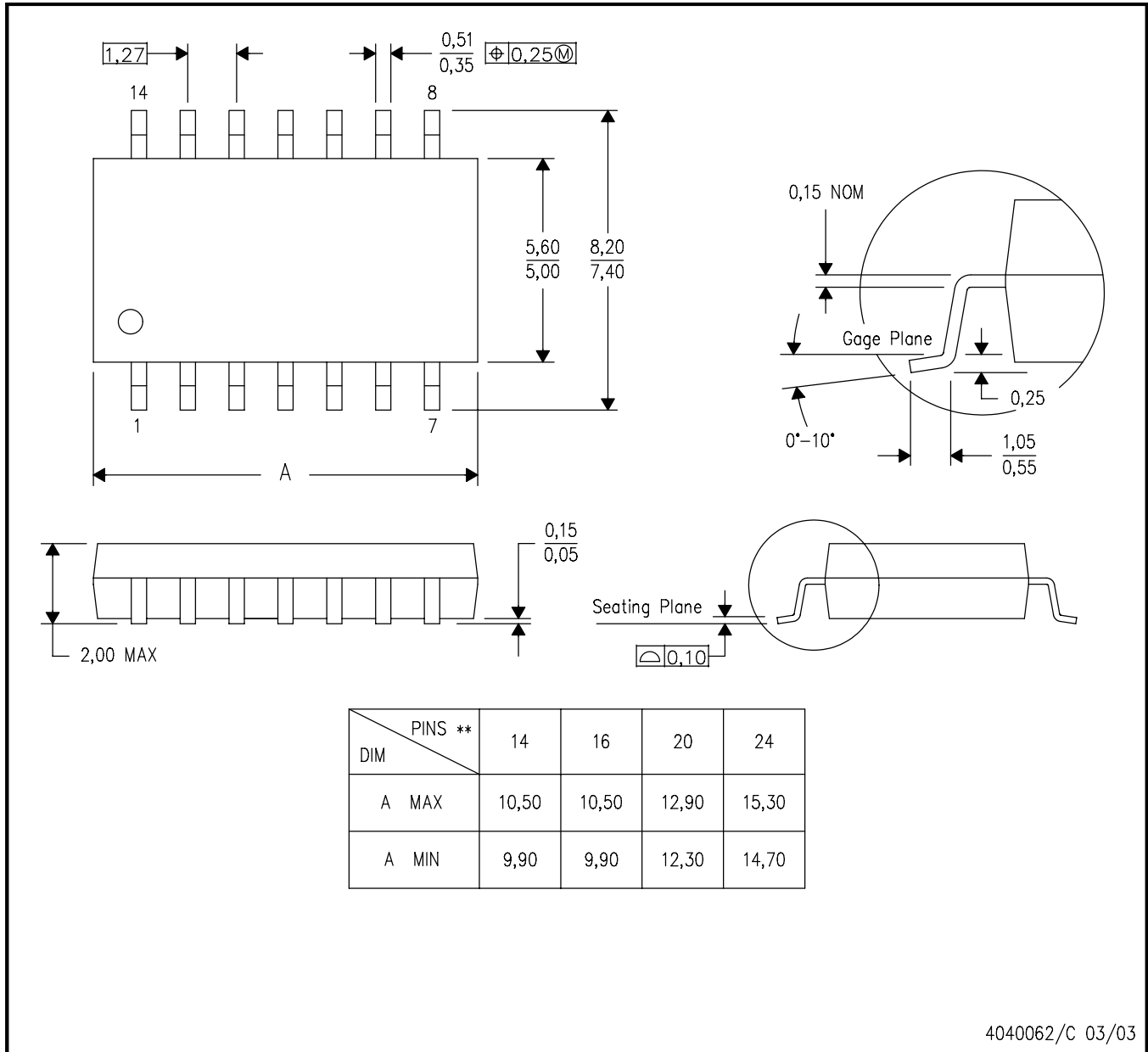
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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